

4800 Bondtester

Advanced Automated Wafer Testing

The Nordson DAGE 4800 is at the forefront of wafer testing technology catering for the testing of wafers from 200mm up to 450mm.

Combining proven technology with the latest Paragon automation software delivers unparalleled accuracy, repeatability and results stability. The Nordson Dage 4800 is truly unique and is the most advanced bondtester on the market.

Superior Quality

Unsurpassed accuracy and repeatability ensures there is total confidence in the quality of test results.

Ultimate Step Back Accuracy

Control of shear height (step back) is critical to consistent test results. Nordson DAGE's unique patented anti backlash system aids setting and controlling shear height leading to step back accuracy up to +/- 0.25 microns.

Advanced Imaging

A range of powerful camera and optical systems optimize load tool alignment, auto programming and post-test analysis.

Debris Removal Station

Quickly and efficiently clears debris automatically from shear and tweezer cartridges.

Unique Dual Microscope Mount

The 4800 bondtester's advanced optics combined with the microscope's dual vibration reduction mount and adjustable eye-line, provides unparalleled image stability.

Precise Alignment for Small Geometries

The unique vector nudge controls, offering key pad operation, feature programmable nudge buttons for precise step movement to ensure ultimate positional accuracy.

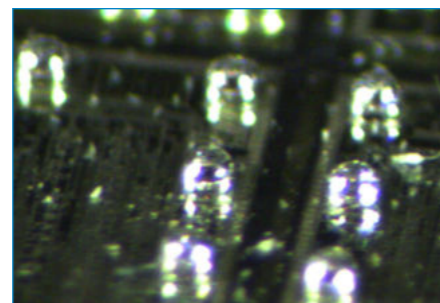
Automated Testing

A fully automated test routine can be configured to run a set of tests on selected or random die, using the intuitive wafer mapping module. Assistance from load to result from Camera Alignment, Failure Mode Assignment and graphical data representation.



Advanced Automated Wafer Testing

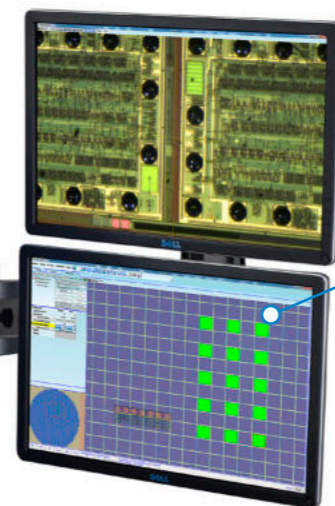
Unique dual microscope mount for high power optics



Interchangeable test cartridges including the patented Multi-Function Cartridge (MFC) and latest high precision tweezer cartridge



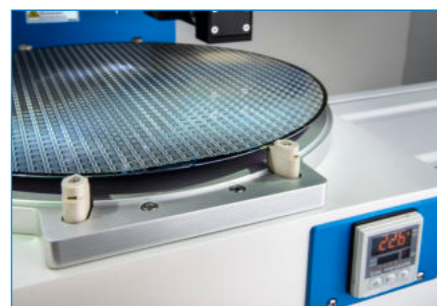
Wafer creation and mapping



Integrated image capture and side alignment cameras



Automatic edge lift smart chuck and high precision XY stage with sub-micron resolution and repeatability



Integrated debris removal station cleans shear and pull tools automatically between tests



Pedigree in Automated Bondtesting

Automation Software

Nordson DAGE Paragon™ test software boasts a highly configurable and intuitive interface as well as a wide variety of advanced functionality, such as automatic GR&R calculation, built-in diagnostics, a range of charts and a unique database search engine wizard. Utilizing the onboard Imaging systems allows for automated alignment via fiducial matching.

Paragon™ provides the ultimate flexibility for wafer map creation enabling quick and precise set-up of test patterns; with virtual images for each test pattern allowing for easy editing. You can select from the following methods:

- Scan the wafer using the unique on-board intelligent automatic wafer mapping software.
- Import wafer maps using industry standard formats
- Use the simple mouse point and click wizard to program any test point anywhere on the wafer

Unparalleled Versatility

The patented industry leading multi-function cartridges expand the versatility of the 4800 bondtester.

Operators can easily identify which transducer is active transducer not in use via the cartridge window whilst the 'Park Position' protects the transducers inside the cartridge.



Existing cartridges, used on the 4000 and 4000Plus bondtesters are also compatible with the 4800 system.

Highlights:

- Ergonomic, low-mass grab handles ensure safe and secure removal
- Quick and easy to interchange with single load cartridges
- Patented air bearing technology for shear testing
- Park position protects transducers
- Transducer application window

Powerful Optical Systems

The 4800 system offers a range of optical solutions:

Image Capture System

Provides high resolution images for failure mode analysis. Built into the system, it's location close to the tool maximizes throughput, particularly for automated tests.

Alignment Camera

A built-in high resolution camera with macro zoom lens and coaxial illumination. Used in conjunction with the image capture system the set-up and use of automation patterns and routines is significantly enhanced.



Integrated image capture and alignment camera

Trinocular Camera

When used with an appropriate microscope the field of view can be adjusted from wide to close up; ideally suited for macro positioning. With the side alignment camera, the front and side view enable precise tool alignment. In addition high power optics can be used to see very small features sub 20 microns aiding operator alignment for shear testing.

Side Alignment Camera

Ideal for testing micro features. The secondary view point provides the ability to do accurate and repeatable testing. It's ultra stable attachment ensures vibration free imaging with constant focus on the tool tip.

Borescope Imaging System

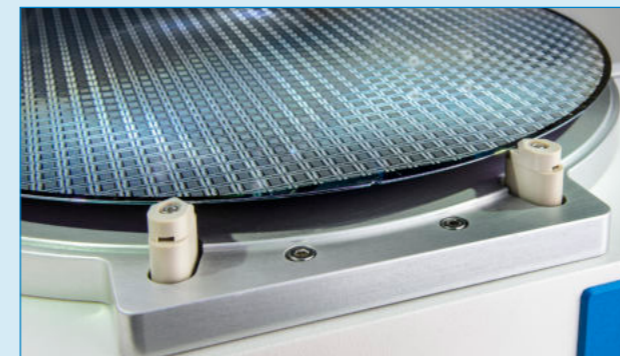
Provides high magnification imaging which is ideal for precise tool alignment. It also enables off line failure mode analysis, test grading and live recording of tests.

Successfully Test Warped and Thin Wafers

The edge lift smart chuck has a unique design where the edge lift pins ensure that warped or thin wafers cannot slide off the chuck. The gradual vacuum pressure enables optimum vacuum on the wafer. Features include:

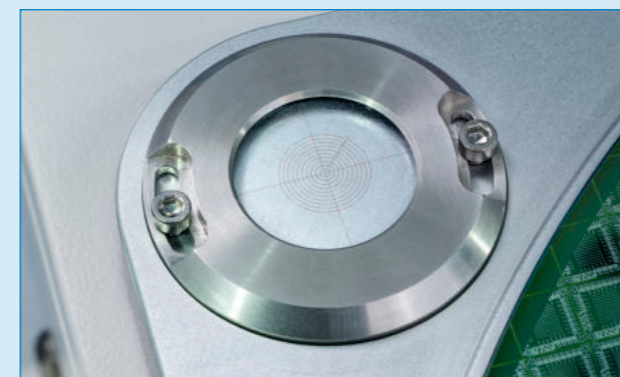
Pre-alignment Accuracy

Lateral movement is eliminated by fully supporting the wafer at the edges. This assures secure wafer placement for every application.



Built-in Cross Hair Camera Alignment Target

This alignment target ensures the operator is 100% confident on the location of the load tool in relation to the chuck. This calibration greatly enhances accuracy.



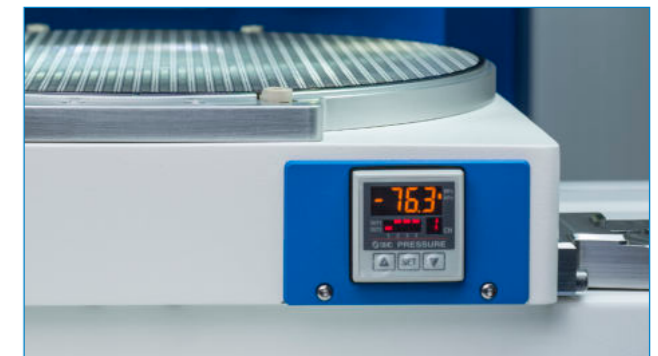
Integrated Calibration

Guaranteed accuracy and confidence in results via built in verification and cartridge calibration.

Intelligent and Intuitive Chuck Controller

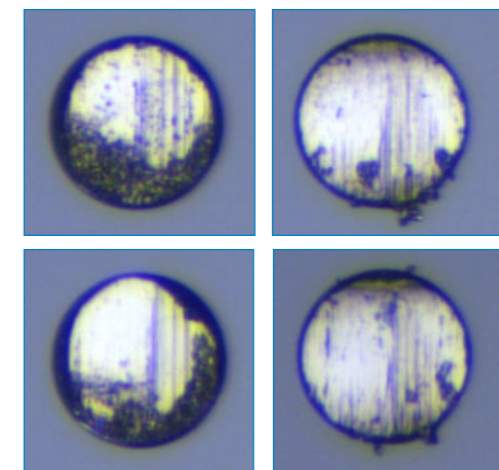
The multi-function programmable controller ensures safe and secure transfer of the wafer. Seamlessly integrated into the Paragon software it provides feedback on the vacuum clamping pressures therefore preventing damage to the wafer.

What's more the operator can easily see continuous feedback of the vacuum and air levels and can therefore take action to prevent damage to the wafer should there be an interruption to the air supply.



Failure Mode Imaging and Grading

The automated image capture system locates the correct position to optimize image quality. An extended depth of field option also produces an automatically focused image and 3D map of the failure.



Typical failure modes

Automated Wafer Testing

Wafer Handler Integration

The Nordson DAGE 4800 integrates with wafer handler systems to ensure reliable and repeatable operation.

Integration with a wafer handler transforms the Nordson DAGE 4800 into a fully automated system ensuring reliable and repeatable operation, utilizing the next generation of bond testing software, Paragon™.

The highly intuitive and configurable interface provides quick and easy automated test routine development and execution for a wide range of sample configurations.

A step by step wizard guides the user through the set up process, catering for a variety of options. Paragon also provides the ability to simultaneously display and record the view from multiple cameras.



Brooks EFEM with Vision™ load port modules

4800 INTEGRA™

The Nordson DAGE 4800 Integra is a complete solution for automated wafer bond testing. The entire system is factory configured and controlled from one PC.

Virtually Operator Free Testing

The system is completely controlled via Paragon™ software and once programmed will perform all parts of the test automatically, with no need for operator input.

Full SECS/GEM Integration

The system connects directly to a network to allow full SECS/GEM operation. When combined with a FOUP loading system, testing, analysis and results can be entirely automated.

Clean Room Compatible

An optional fan filter unit and front doors can be added with Ionizers for clean room operation.



Automatic Wafer Justifier

The wafer justifier ensures warped wafers can be automatically clamped to the vacuum chuck prior to testing.

Fan Filter Unit

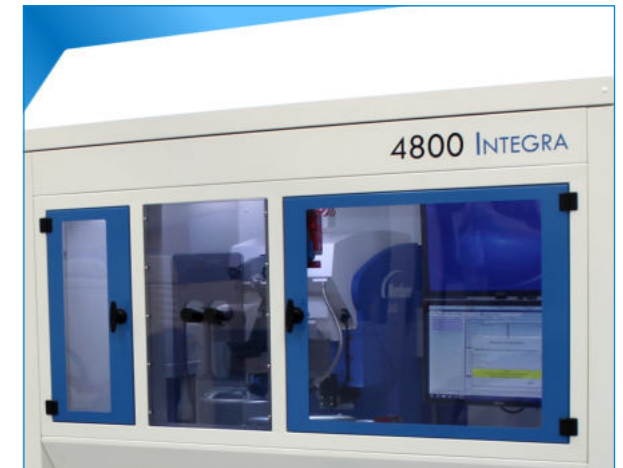
The 4800 Integra can be fitted with a fan filter unit and enclosed doors. This allows for a positive pressure to be kept inside the system to keep debris out of the test area.

Interlock Options

Light curtains or interlocked doors can be fitted and are used to protect operators from the test area. If broken or opened the system will pause the current test and restart once the obstruction is removed.

CCD Camera Monitoring

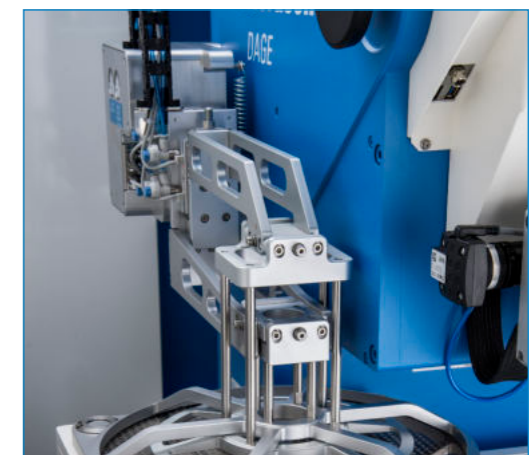
Optional CCD cameras can be fitted to the wafer handler and inside the 4800 Integra. This allows for monitoring and recording of the test process.



Fan filter unit and enclosed doors



Light curtain or interlocked doors



Automatic wafer justifier

Specifications at a Glance

Size	All configurations:- 1075 x 980 x 855 (ex PC)
Weight	170Kg
Power supply	90 - 264V AC, 47 - 63 Hz, Single Phase, Universal
Pneumatic supply	Minimum 4 bar, 6mm OD / 4mm ID plastic pipe
Vacuum supply	Minimum 67kPa, 6mm OD / 4mm ID plastic pipe
Interfaces	USB, Gigabit Ethernet
XY Stage	550mm X travel
	410mm Y travel
	High resolution linear encoders
Z Axis	75mm Z Travel
Total system accuracy (see detailed load cartridge specifications)	up to +/- 0.05% FSD (See cartridge specification)
Optical / camera systems	Integrated image capture
	High power microscope
	Trinocular camera
	Alignment camera (large FOV)
	Side alignment camera
	Borescope
Test Modes	Manual operation
	Semi-automatic
	Fully-automatic via fiducial and pattern recognition
	Onboard wafer map creation
	Wafer map download
Software	Paragon™
	SECS/GEM (Please consult factory)
Wafer Loading	Manual via carrier frame
	Fully automatic, load from left or right (factory configured)
	EFEM
Compliance	European Directives
	Machinery Directive (2006/42/EC)
	Low Voltage Directive (2006/95/EC)
	EMC Compatibility (2004/108/EC)
	RoHS (2002/95/EC)
	CE Declaration of Conformity
	ISO 9001:2008
	SEMI (S2)

Americas	+ 1 760 930 3307 sales@nordsondage.com
Europe	+ 44 1296 317800 globalsales@nordsondage.com
China	+86 512 6665 2008 sales.ch@nordsondage.com
Germany	+49 89 2000 338 270 sales.de@nordsondage.com
Japan	+81 3 3 3599 5920 sales.jp@nordsondage.com
South East Asia	+65 6552 7533 sales.sg@nordsondage.com
Taiwan	+886 2 2902 1860 globalsales@nordsondage.com
United Kingdom	+44 1296 317800 globalsales@nordsondage.com

A Partner You Can Trust

Nordson DAGE is the market leading provider of award winning test and inspection systems for destructive and non-destructive mechanical testing of electronic components and are experts in inspection technology, taking pride in delivering support to multinational organisations globally. Founded in 1961, with global headquarters in Aylesbury, UK, Nordson DAGE is part of the Nordson Corporation, which has direct operations in more than 30 countries.

Global Support and Complete Peace of Mind

Fully inclusive service and support programs available.



LRQ 4009487 BS EN ISO 9001: 2008

Specifications subject to change without prior notice. Copyright © Nordson DAGE 2016. Other products and company names mentioned are trademarks or trade names of their respective companies.

Nordson DAGE products are patent protected and covered by the patent listed at www.nordson.com/dagepatents.